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### IRFR210B / IRFU210B

#### 200V N-Channel MOSFET

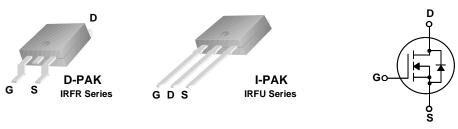
#### **General Description**

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supply and motor control.

#### **Features**

- 2.7A, 200V,  $R_{DS(on)}$  = 1.5 $\Omega$  @V<sub>GS</sub> = 10 V Low gate charge ( typical 7.2 nC)
- Low Crss (typical 6.8 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability



#### Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		IRFR210B / IRFU210B	Units
V <sub>DSS</sub>	Drain-Source Voltage		200	V
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°C)		2.7	Α
	- Continuous (T <sub>C</sub> = 100°C)		1.7	Α
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	10	Α
V <sub>GSS</sub>	Gate-Source Voltage		± 30	V
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	40	mJ
I <sub>AR</sub>	Avalanche Current	(Note 1)	2.7	Α
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	2.6	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *		2.5	W
	Power Dissipation (T <sub>C</sub> = 25°C)		26	W
	- Derate above 25°C		0.2	W/°C
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Temperature Range		-55 to +150	°C
T <sub>L</sub>	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

#### **Thermal Characteristics**

\* When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		4.9	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

Symbol	Parameter	Test Conditions		Min	Тур	Max	Units
Off Cha	aracteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		200			V
$\Delta BV_{DSS}$ / $\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to	o 25°C		0.2		V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V				10	μΑ
		V <sub>DS</sub> = 160 V, T <sub>C</sub> = 125°C				100	μΑ
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V				100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
On Cha	racteristics						
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10 V, I <sub>D</sub> =1.35 A			1.16	1.5	Ω
9 <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 40 V, I <sub>D</sub> = 1.35 A	(Note 4)		2.25		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz	-		175 30 6.8	225 40 9.0	pF pF
	ing Characteristics				0.0	0.0	P.
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 100 \text{ V}, I_{D} = 3.3 \text{ A},$ $R_{G} = 25 \Omega$			5.2	20	ns
t <sub>r</sub>	Turn-On Rise Time				35	80	ns
t <sub>d(off)</sub>	Turn-Off Delay Time				20	50	ns
t <sub>f</sub>	Turn-Off Fall Time	(1	Note 4, 5)		25	60	ns
Qg	Total Gate Charge	$V_{DS} = 160 \text{ V}, I_D = 3.3 \text{ A},$ $V_{GS} = 10 \text{ V}$ (Note 4, 5)		!	7.2	9.3	nC
$Q_{gs}$	Gate-Source Charge				1.3		nC
$Q_{gd}$	Gate-Drain Charge				3.5		nC
Drain-S	Source Diode Characteristics a	nd Maximum Ratings					
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current					2.7	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F					10	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 2.7 \text{ A}$				1.5	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_{S} = 3.3 \text{ A},$			106		ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl <sub>F</sub> / dt = 100 A/μs	(Note 4)		0.37		μС

- **Notes:** 1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 8.2mH, I $_{AS}$  = 2.7A, V $_{DD}$  = 50V, R $_{G}$  = 25  $\Omega$ , Starting T $_{J}$  = 25°C 3. I $_{SD}$   $\leq$  3.3A, di/dt  $\leq$  300A/ $\mu$ s, V $_{DD}$   $\leq$  BV $_{DSS}$ , Starting T $_{J}$  = 25°C 4. Pulse Test : Pulse width  $\leq$  300 $\mu$ s, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

### **Typical Characteristics**

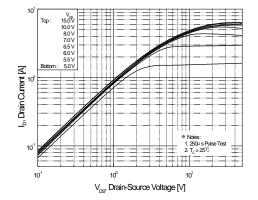


Figure 1. On-Region Characteristics

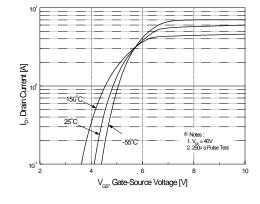


Figure 2. Transfer Characteristics

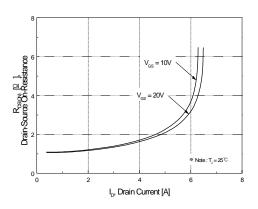


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

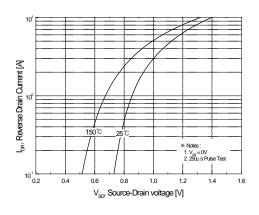


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

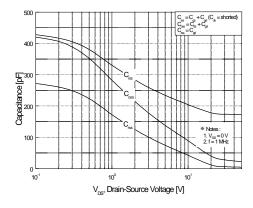


Figure 5. Capacitance Characteristics

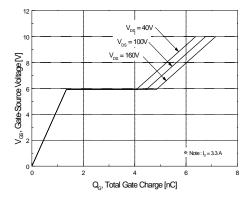
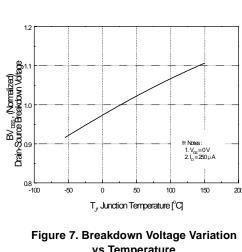
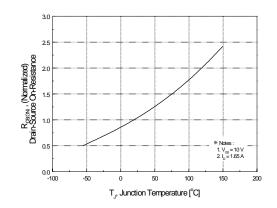


Figure 6. Gate Charge Characteristics

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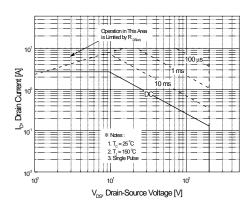


Typical Characteristics (Continued)



vs Temperature

Figure 8. On-Resistance Variation vs Temperature



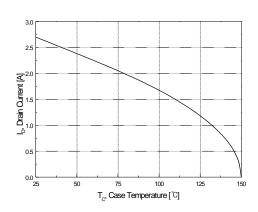


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs Case Temperature

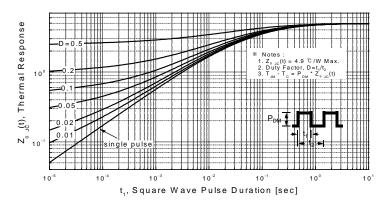
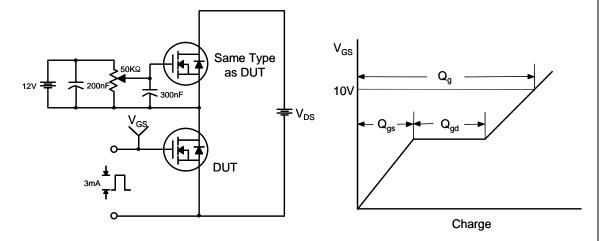
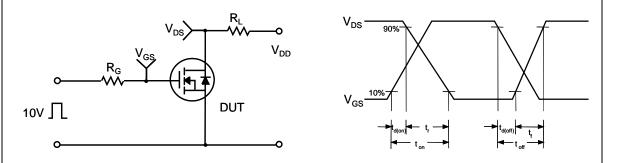


Figure 11. Transient Thermal Response Curve

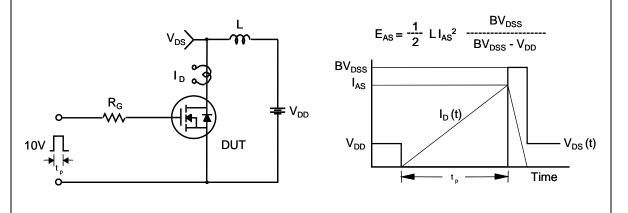
#### **Gate Charge Test Circuit & Waveform**



#### **Resistive Switching Test Circuit & Waveforms**



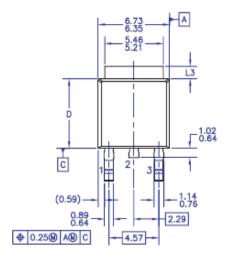
#### **Unclamped Inductive Switching Test Circuit & Waveforms**

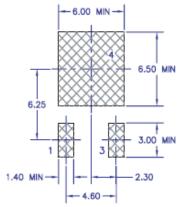


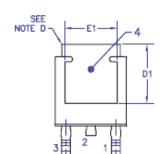
## Peak Diode Recovery dv/dt Test Circuit & Waveforms DUT I<sub>SD o</sub> Driver Same Type as DUT $V_{DD}$ • dv/dt controlled by R<sub>G</sub> • I<sub>SD</sub> controlled by pulse period Gate Pulse Width $V_{GS}$ Gate Pulse Period 10V (Driver) I<sub>FM</sub> , Body Diode Forward Current I<sub>SD</sub> di/dt (DUT) $\mathsf{I}_{\mathsf{RM}}$ **Body Diode Reverse Current** V<sub>DS</sub> (DUT) Body Diode Recovery dv/dt **Body Diode** Forward Voltage Drop

#### **Mechanical Dimensions**

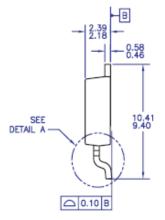
#### D - PAK

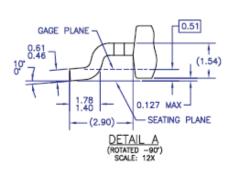












Dimensions in Millimeters

# **Mechanical Dimensions** I - PAK ►A. 6.80 6.35 2.50 2.10 5.54 5.14 1.27 0.50 0.60 0.40 6.30 5.90 - 1.52 0.70 - 2.28 - 1.60 Ţ 3 2 1.14 0.76 9.65 8.90 1.14 0.90 2.29 (0.60) -0.60 0.88 0.64 <del>0</del>0.250**0**0 A0**0**0 C 3 PLCS Dimensions in Millimeters

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